

# **Multilayer Power Inductor**

# **CIG22E\_MAE Series(2520/ EIA 1008)**

#### **APPLICATION**

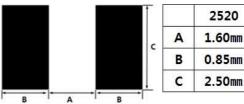
Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

### **FEATURES**

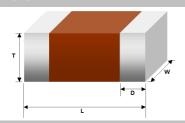
- High Efficiency (High Q)
- Low Profile( 0.9mm max.)
- · Magnetically shielded structure
- Free of all RoHS-regulated substances
- · Monolithic structure for high reliability



# TOO MINIERDED EARD PATTERN



#### DIMENSION



TYPE	Dimension [mm]				
IIFE	L	W	Т	D	
22	2.5±0.2	2.0±0.2	0.8±0.1	0.55±0.25	

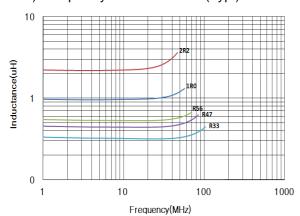
#### DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A)*1 Typ.	Rated Current (A)*2  Max.
CIG22ER33MAE	1008/2520	0.33 ±20 %	0.060 ±20%	4.80	2.0
CIG22ER47MAE	1008/2520	0.47 ±20 %	0.060 ±25%	4.05	2.0
CIG22ER56MAE	1008/2520	0.56 ±20 %	0.075 ±20%	4.10	1.9
CIG22E1R0MAE	1008/2520	1.0 ±20 %	0.090 ±20%	2.30	1.9
CIG22E2R2MAE	1008/2520	2.2 ±20 %	0.146 ±20%	1.05	1.3

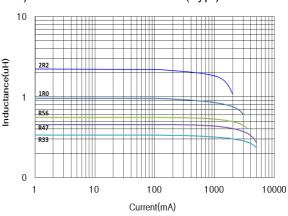
- \*Rated Current (A)\*1: DC current value when Inductance drops to 30% of nominal Inductance value (ONLY REFERENCE)
- MOPERATING TEMPERATURE TRANSPORT TO THE PROPERTY OF T
- \*\*Test equipment: Agilent :E4991A+16092A

# CHARACTERISTIC DATA

## 1) Frequency characteristics (Typ.)



## 2) DC Bias characteristics (Typ.)







CI	G	22	E	1R0	M	Α	Ε
(1)	(2)	(3)	(4)	(5)	(6)	<b>(7)</b>	(8)

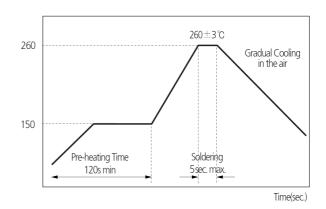
- (1) Chip Inductor
- (3) Dimension
- (5) Inductance (1R0:1.0uH)

- (2) Power Inductor
- (4) Product Series (E:High Current Type)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

# **REFLOW SOLDERING**

### Soldering 260+0/-5°C 10 sec. max. Temp.(℃) Gradual 260 Cooling 230 in the air 180 150 Soldering Pre-heating 60s max 60~120s 30~60s Time(sec.)

## FLOW SOLDERING



Packaging Style	Quantity(pcs/reel)
Embossed Taping	3,000pcs

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.